

**Appl. No.** : **Unknown**  
**Filed** : **Herewith**

## **AMENDMENTS TO THE SPECIFICATION**

Please delete paragraphs 13, 18-20, 25, 41-65, and 108-144.

Please replace paragraph [0001] with the following amended paragraph:

[0001] This application is a divisional of copending application 10/243,579 filed September 13, 2002, which is a continuation of copending application 09/932,795 filed August 17, 2002, which is a divisional of application 09/605,094 filed June 27, 2000, now U.S. Patent No. 6,113,702, which claims the priority benefit of Provisional application 60/039,850 filed March 5, 1997 and is a continuation-in-part of abandoned application 08/788,817 filed January 23, 1997, which is a continuation-in-part of application 08/706,069 filed August 30, 1996, now U.S. Patent no. 6,053,982, which claims the priority benefit of Provisional Application No. 60/003,132, filed September 1, 1995.

Please replace paragraph [0011] with the following amended paragraph:

[0011] The present invention embodies a susceptor which supports a wafer spaced therefrom and effectively decouples conductive heat transfer between the two elements. The wafer is supported on ~~one or more~~ spacers in a recess preferably in an upper surface of the susceptor, the top plane of the wafers preferably being approximately level with an outer ledge of the susceptor. ~~In one arrangement, spacer pins are utilized, and in another a single spacer ring is used.~~ The susceptor preferably includes a plurality of interior passages opening into the recess at a plurality of small sweep gas holes. A sweep gas flows through the susceptor and out the holes and protects the back side of the wafer from deposition gas and particulate contamination. The sweep gas is heated as it flows through the susceptor so as not to cause localized cooling of the wafer and possible areas of slip.

Please replace paragraph [0012] with the following amended paragraph:

[0012] In one embodiment, the susceptor is formed by top and bottom mating sections and the internal passages are formed by grooves in one of the juxtaposed surfaces of the two sections. Desirably, a multi-armed member supports and rotates the susceptor, the member

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preferably being substantially transparent to radiant energy. The arms of the support member are preferably hollow and deliver sweep gas to the lower surface of the susceptor at apertures in communication with the internal passages. Some of the sweep gas may be diverted to exit the susceptor proximate the ~~spacer pins~~ spacers to provide sweep gas protection therearound at all times.

Please replace paragraph [0039] with the following amended paragraph:

[0039] Figure 16 is a top plan view of a third version of the top section of the segmented susceptor for use in the wafer support system of Figure 11; and

Please replace paragraph [0040] with the following amended paragraph:

[0040] Figure 17 is a top plan view of a fourth version of the top section of the segmented susceptor for use in the wafer support system of Figure 11[;].

Please replace paragraph [0066] with the following amended paragraph:

[0066] Figure 1 illustrates a reactor chamber 20 for processing semiconductor wafers, within which a wafer support system 22 of the present invention is incorporated. Prior to discussing the details of the wafer support system 22, the elements of the reaction chamber 20 will be described. The support system is suitable for many types of wafer processing systems, ~~another one being shown in Figures 18 and 19,~~ and the discussion herein should not be limited to one particular type of reaction chamber.

Please replace paragraph [0145] with the following amended paragraph:

[0145] Although this invention has been described in terms of certain preferred embodiments, other embodiments are also within the scope of this invention. For example, although some of the illustrated embodiments are described for specific sizes of wafers, the same features may also be used to accommodate larger wafers. Indeed, wafers of 300 mm or larger are presently contemplated to supplement traditional 200 mm and smaller sized wafers. ~~With larger wafers it may be desirable to employ additional spacers in a ring spaced radially inwardly from~~

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~~the three spacers 100 shown in figure 18, and offset circumferentially to be between the spacers of Figure 18.~~